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## MEMS Material Properties

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## Material Properties for MEMS

Material	Density, $\rho$ , Kg/m <sup>3</sup>	Modulus, E, GPa	$E/\rho$ GN/kg-m
Silicon	2330	165	72
Silicon Oxide	2200	73	36
Silicon Nitride	3300	304	92
Nickel	8900	207	23
Aluminum	2710	69	25
Aluminum Oxide	3970	393	99
Silicon Carbide	3300	430	130
Diamond	3510	1035	295

Units: (m/s)<sup>2</sup>  
↓  
 $\sqrt{E/\rho}$  is acoustic velocity

[Mark Spearing, MIT]

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## Young's Modulus Versus Density

[Ashby, Mechanics of Materials, Pergamon, 1992]

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## Yield Strength

- Definition:** the stress at which a material experiences significant plastic deformation (defined at 0.2% offset pt.)
- Below the yield point:** material deforms elastically → returns to its original shape when the applied stress is removed
- Beyond the yield point:** some fraction of the deformation is permanent and non-reversible

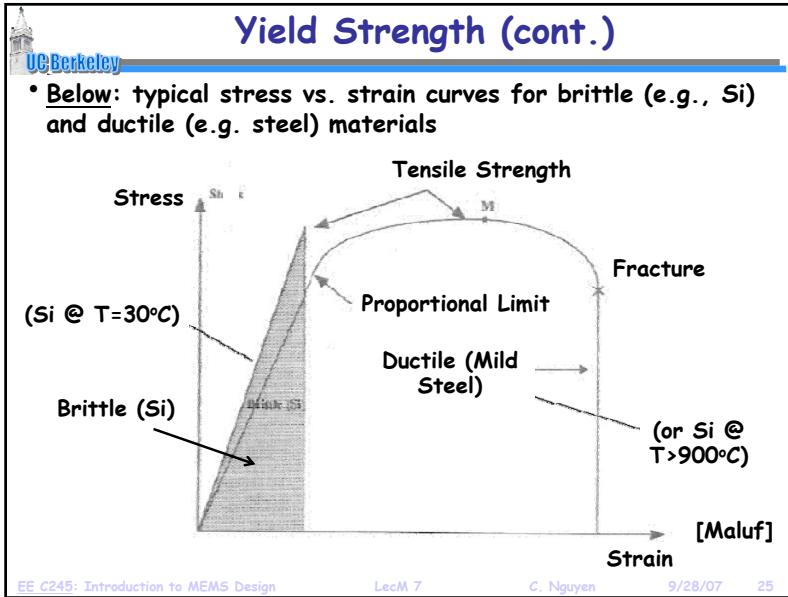
**Yield Strength:** defined at 0.2% offset pt.

**Elastic Limit:** stress at which permanent deformation begins

**Proportionality Limit:** point at which curve goes nonlinear

**True Elastic Limit:** lowest stress at which dislocations move

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### Young's Modulus and Useful Strength

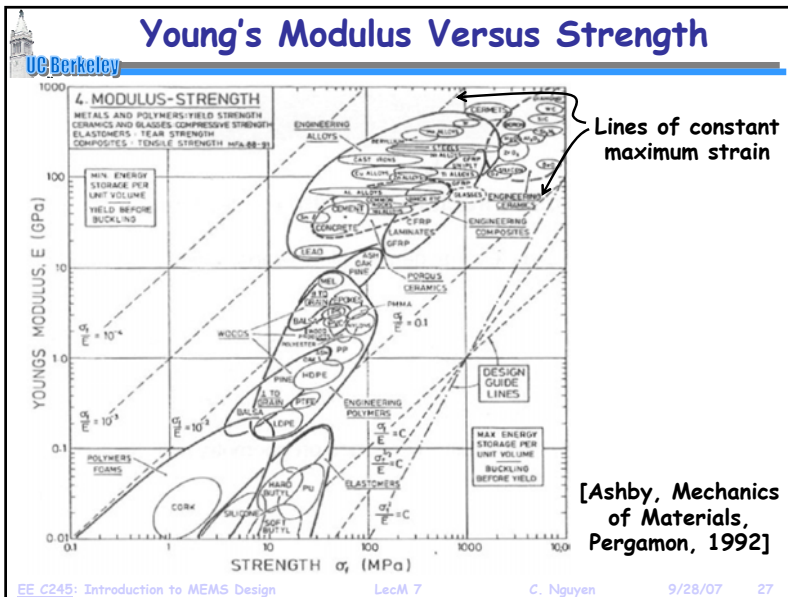
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Stored mechanical energy  $\rightarrow \frac{\sigma_f^2}{E}$

Material	Modulus, E, GPa	Useful Strength*, $\sigma_f$ , MPa	$\frac{\sigma_f}{E}$ (-) $\times 10^{-3}$	$\frac{\sigma_f^2}{E}$ MJ/m <sup>3</sup>
Silicon	165	4000	24	97
Silicon Oxide	73	1000	13	14
Silicon Nitride	304	1000	3	4
Nickel	207	500	2	1.2
Aluminum	69	300	4	1.3
Aluminum Oxide	393	2000	5	10
Silicon Carbide	430	2000	4	9.3
Diamond	1035	1000	1	0.9

From Mark Spearing, MIT, *Future of MEMS Workshop*, Cambridge, England, May 2003

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### Quality Factor (or Q)

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Quality Factor (or Q)

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### Clamped-Clamped Beam $\mu$ Resonator

**Frequency:**  
Stiffness  $k_r = \frac{Eh^3}{12L_r^3}$   
Young's Modulus  $E$   
Density  $\rho$   
Mass  $m_r = \rho L_r W_r h$   
 $f_o = \frac{1}{2\pi} \sqrt{\frac{k_r}{m_r}} = 1.03 \sqrt{\frac{Eh}{\rho L_r^2}}$

**Note:** If  $V_P = 0V \Rightarrow$  device off

$i_o = V_P \frac{dC}{dt}$

Smaller mass  $\Rightarrow$  higher freq. range and lower series  $R_x$   
(e.g.,  $m_r = 10^{-13}$  kg)

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### Quality Factor (or Q)

- Measure of the frequency selectivity of a tuned circuit
- Definition:**  
 $Q = \frac{\text{Total Energy Per Cycle}}{\text{Energy Lost Per Cycle}} = \frac{f_o}{BW_{3dB}}$
- Example: series LCR circuit**  
 $Q = \frac{\text{Im}(Z)}{\text{Re}(Z)} = \frac{\omega_o L}{R} = \frac{1}{\omega_o CR}$
- Example: parallel LCR circuit**  
 $Q = \frac{\text{Im}(Y)}{\text{Re}(Y)} = \frac{\omega_o C}{G} = \frac{1}{\omega_o LG}$

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### Selective Low-Loss Filters: Need Q

**General BPF Implementation:** Resonator Tank - Coupler - Resonator Tank - Coupler - Resonator Tank

**Typical LC implementation:**

- In resonator-based filters: high tank  $Q \Leftrightarrow$  low insertion loss
- At right: a 0.1% bandwidth, 3-res filter @ 1 GHz (simulated)  
 $\Rightarrow$  heavy insertion loss for resonator  $Q < 10,000$

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### Oscillator: Need for High Q

- Main Function:** provide a stable output frequency
- Difficulty:** superposed noise degrades frequency stability

**Ideal Sinusoid:**  $v_o(t) = V_o \sin(2\pi f_o t)$

**Real Sinusoid:**  $v_o(t) = (V_o + \epsilon(t)) \sin(2\pi f_o t + \theta(t))$

**Higher Q**  $\Rightarrow$  **Tighter Spectrum**

Zero-Crossing Point

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